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| Application Serial No | October 2, 2000 |
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| Inventor | Guy T. Blalock |
| Inventor | Micron Technology Inc. |
| Assignee | Which of recimology, mo. |
| Group Art Unit | , 1/65 |
| Examiner | t an Vinh |
| Examiner | MICO 4544 |
| Attorney's Docket No | |
| Allomey's Dooker No. 11111111111111111111111111111111111 | = |
| Title: Plasma Etching Methods | TEC |

RESPONSE TO MARCH 29, 2002 OFFICE ACTION

To:

Box Fee Amendment

Assistant Commissioner for Patents

Washington, D.C. 20231

From:

D. Brent Kenady (Tel. 509-624-4276; Fax 509-838-3424)

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AMENDMENTS

In the Specification

At page 1, before the "Technical Field" section, please replace the existing Related Applications section with the following:

--RELATED PATENT DATA

This patent is a continuation application of U.S. Patent Application Serial No. 09/141,775, which was filed on August 27, 1998, entitled "Plasma Etching Methods", naming Guy T. Blalock, David S. Becker and Kevin G. Donohoe as inventors, and which is now U.S. Patent No. 6,277,759, the disclosure of which is incorporated by reference.--